<u> </u>	FLH Ref. No.: 450101-410
	ET U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
To the Honorable Commissioner of Pa. 1009545	49 attached original documents or copy thereof.
1. Name of conveying party(ies)	2. Name and address of receiving party(ies)
Tomoo HAYAKAWA	Name: SONY CORPORATION 7-35 Kitashinagawa 6-chome Shinagawa-Ku, Tokyo 100-31, Japan
Additional name(s) of conveying party(ies) attached?  Yes X No	Additional name(s) & address(es) attached? Yes _x No
3. Nature of conveyance: 1-38-99 (IAN 2	8 1980
Security Agreement Merger Change of Name Other	
Execution Date: August 18, 1998	
4. Application number(s) or patent number(s):  If this document is being filed together with a new application, the execution date of the application is:  A. Int'l Patent Application No.(s) PCT/JP97/03091 (USSN 09/068,236) filed 3 September 1997  Additional numbers attached? Yes X No	
<ol><li>Name and address of party to whom correspondence concerning document should be mailed:</li></ol>	6. Total number of applications and patents involved 1
Name: WILLIAM S. FROMMER	7. Total fee (37 CFR 3.41)
Internal Address: FROMMER LAWRENCE & HAUG LLP	X Enclosed Authorized to be charged to
Street Address: 745 FIFTH AVENUE	deposit account 50-0320
City: <u>NEW YORK</u> State: <u>N.Y.</u> Zip: <u>10151</u>	<ol><li>Deposit account number: (Attach duplicate copy of this page if paying by deposit account)</li></ol>
Do not use	this space
9. Statement and signature. To the best of my knowledge and belief, the foregoing inforcopy of the original document.  WILLIAM S. FROMMER	Zest January 20, 1999
Name of Person Signing Signa	ture Date Total number of pages including cover

Commissioner of Patents and Trademarks Box Assignments Washington, D.C. 20231

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sheet, attachments, and document: 2

## ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

## DATA ENCODING METHOD AND DATA ENCODING APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the dates indicated below.

inis assignment executed on the dates indicated below.	
Tomoo HAYAKAWA	august 18, 1998
Name of first or sole inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of first or sole inventor, Lomoo Hansakawa	august 18, 1998
Signature of first or sole inventor	Date of this assignment
Name of second inventor	Execution date of U.S. Patent Application
Residence of second inventor	
Signature of second inventor	Date of this assignment
Name of third inventor	Execution date of U.S. Patent Application
Residence of third inventor	
Signature of third inventor	Date of this assignment

Page 1 of 1

PATENT REEL: 9726 FRAME: 0135

**RECORDED: 01/28/1999**